

SL13-M

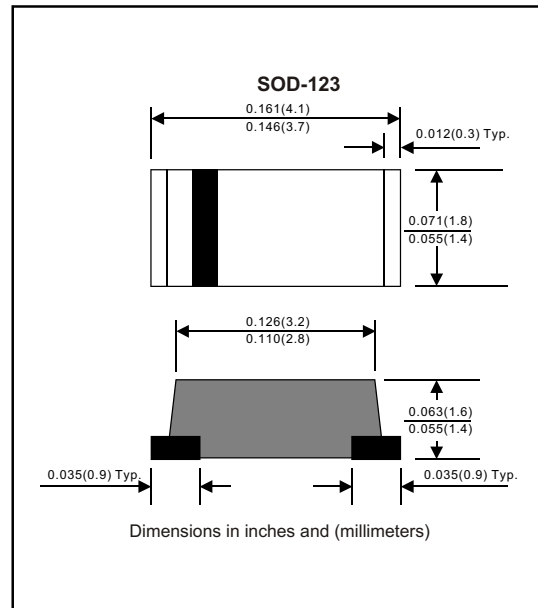
Silicon epitaxial planer type

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0 Utilizing Flame Retardant Epoxy Molding Compound.
- For surface mounted applications.
- Exceeds environmental standards of ML-S-19500 / 228
- Low leakage current

Mechanical data

Case : Molded plastic, JEDEC SOD123 / MNI SMA
 Terminals : Solder plated, solderable per ML-STD-750, Method 2026
 Polarity : Indicated by cathode band
 Mounting Position : Any
 Weight : 0.04 gram



MAXIMUM RATINGS (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current 50 Hz sine wave , R-load	On alumina substrate	I _O			1.29	A
	T _L = 129°C On glass-epoxy substrate				1.1	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			30	A
Reverse current	V _R = V _{RRM} T _A = 25°C	I _R			0.5	mA
	V _R = V _{RRM} T _A = 100°C				10	mA
Thermal resistance	Junction to ambient	R _{JA}		42		°C / w
Diode junction capacitance	f=1MHz and applied 10vDC reverse voltage	C _J		90		pF
Storage temperature		T _{STG}	-55		+150	°C

SYMBOLS	MARKING CODE	V _{RRM} *1 (V)	V _{RMS} *2 (V)	V _R *3 (V)	V _F *4 (V)	Operating temperature (°C)
SL13-M	L3	30	21	30	0.40	-55 to +125

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage

RATING AND CHARACTERISTIC CURVES (SL13-M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

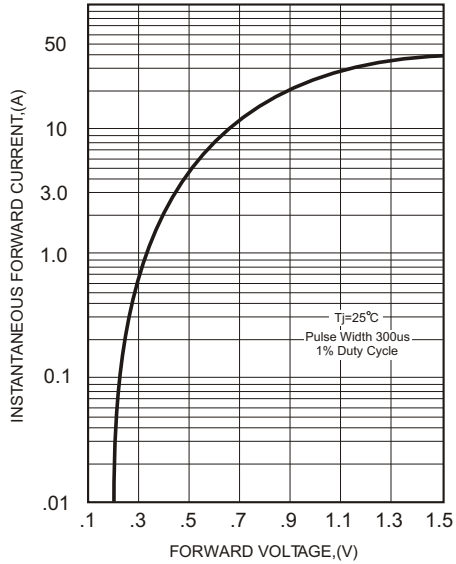


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

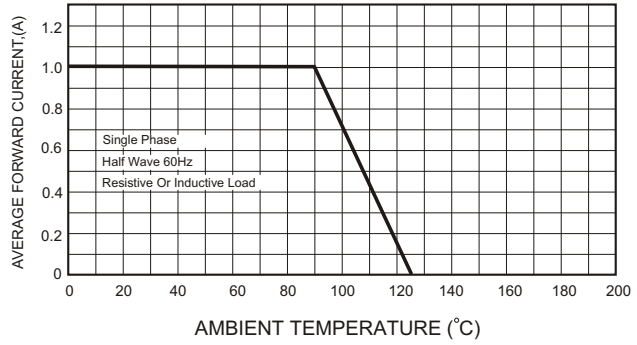


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

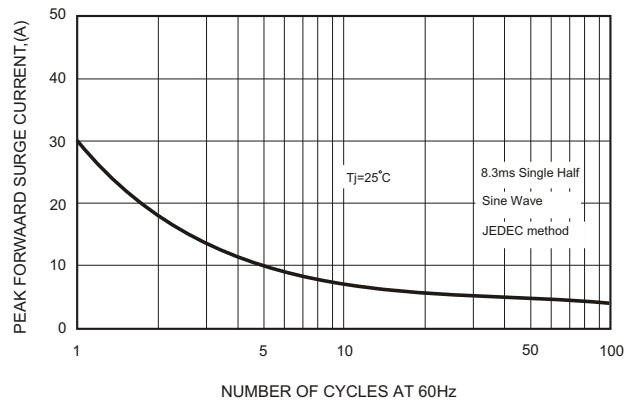


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

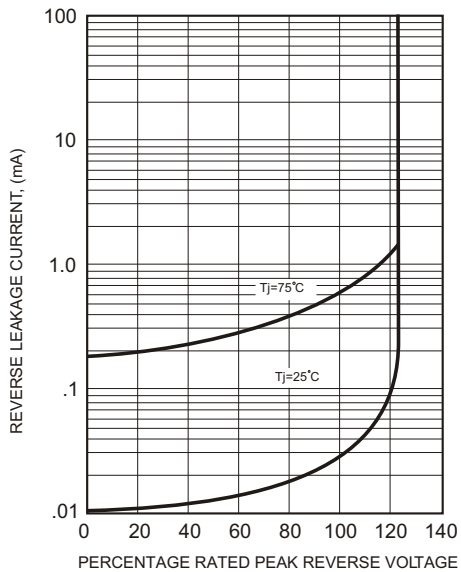


FIG.5-TYPICAL JUNCTION CAPACITANCE

